

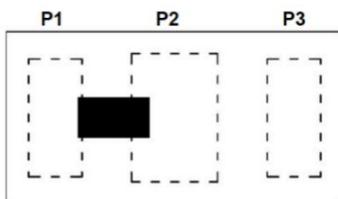
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

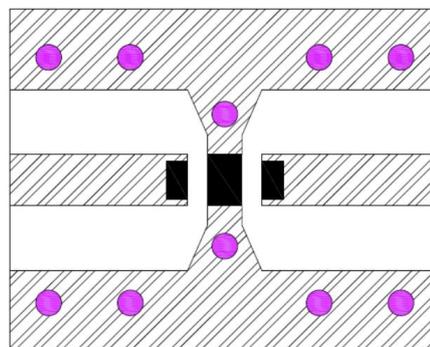
NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	4950~5950	-	1.0	1.3
2	Insertion Loss (dB) -40 ~ +90 °C	4950~5950	-		1.5
3	VSWR	4950~5950		1.3	2.0
4	Attenuation (dB)	30~2700	38	42	-
		3453~3574	20	35	-
		3667~3883	35	40	-
		8600~9750	32	35	-
		10600~11650	25	30	-
		15540~17760	18	21	-
Operating & Storage Condition (Component) Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C~ +85°C					
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 °C Humidity: 30 to 70% relative humidity					

Construction



PIN	Connection
1	Input port
2	GND
3	Output port

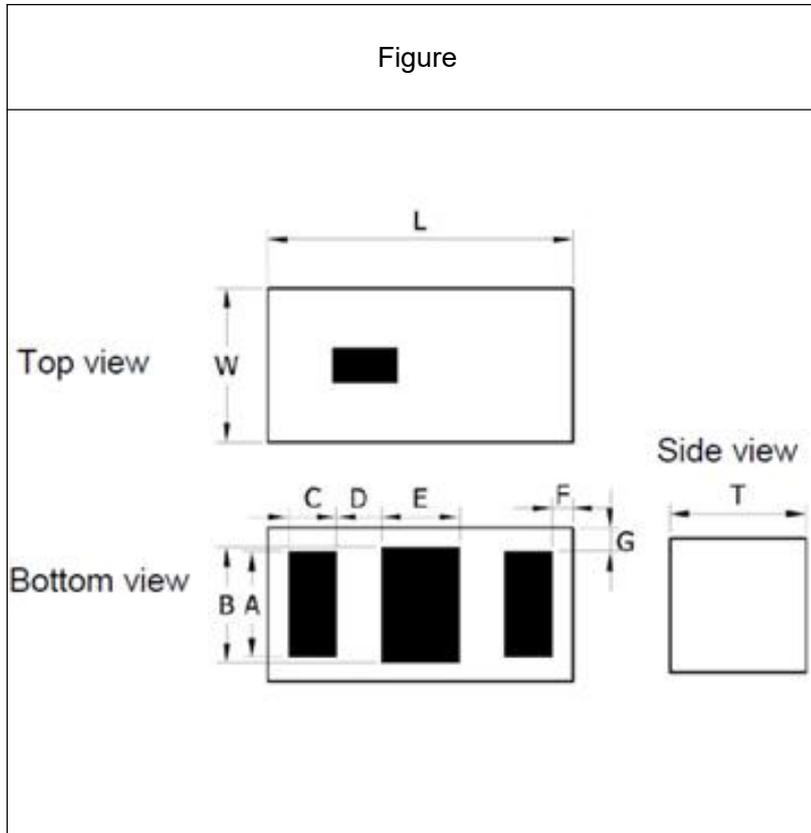
Mounting Considerations



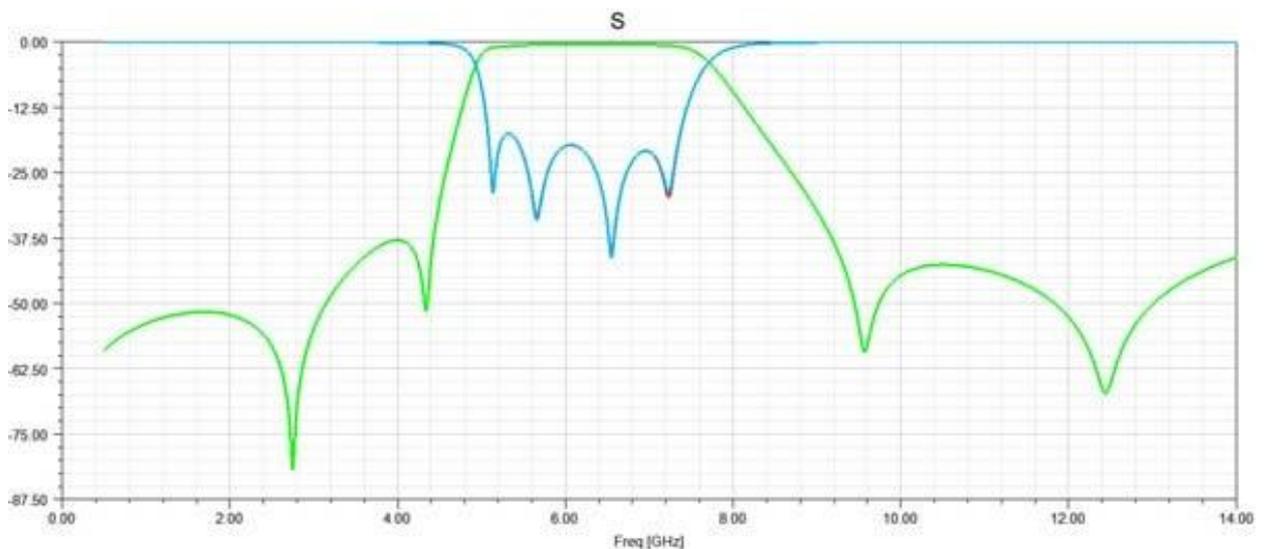
- Land
- ▨ Solder
- Through-hole

Unit: mm
Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
 <p>Top view</p> <p>Bottom view</p> <p>Side view</p>	L	1.60±0.10
	W	0.80±0.10
	T	0.65max.
	A	0.55±0.10
	B	0.60±0.10
	C	0.25±0.10
	D	0.23±0.10
	E	0.40±0.10
	F	0.12±0.10
G	0.125±0.10	

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.